

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	145	257/930.ccls. and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:49
L2	1	L1 and flip	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:01
L3	0	peltier and (flip near (chip or die)) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:46
L4	23	peltier and (flip near (chip or die)) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:48
L5	361	(peltier with (heat or heating)) and (chip or die) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:20
L6	361	L5 and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:54
L7	109	(peltier with ((heat or heating) and (chip or die))) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:50
L8	14	L7 and ((substrate or board or interposer or pwb or pcb) with ("si" or silicon))	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:51
L9	32	("5229327").URPN.	USPAT	OR	OFF	2005/02/24 14:58

L10	73	("3923567"   "3959047"   "3982268"   "4081701"   "4394712"   "4595428"   "4631636"   "4653025"   "4710798"   "4713841"   "4739446"   "4870470"   "4977439"   "5061987"   "5079618"   "5153814"   "5168334"   "5229327"   "5258648"   "5275001"   "5313361"   "5317197"   "5343366"   "5352998"   "5362976"   "5392407"   "5409547"   "5415699"   "5432823"   "5438224"   "5468681"   "5532506"   "5567654"   "5574923"   "5587119"   "5598031"   "5598039"   "5610366"   "5618752"   "5622875"   "5633962"   "5637828"   "5646067"   "5656548"   "5657481"   "5682062"   "5692558"   "5699073"   "5699291"   "5714791"   "5747728"   "5753529"   "5767001"   "5781746"   "5786628"   "5807783"   "5821624"   "5834799"   "5855735"   "5861666"   "5901050"   "5902118"   "5903018"   "5903045"   "5915167"   "5990550"   "5990564"   "5991161"   "6016256"   "6137164"   "6219237"   "6223273"   "6281042").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/24 15:20
L11	356	L6 not L10	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:21
L12	1697	((substrate or board or interposer or pwb or pcb) with ("si" or silicon)) and (flip near (chip or die)) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:46
L13	860	((substrate or board or interposer or pwb or pcb) near ("si" or silicon)) and (flip near (chip or die)) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:53

L14	246	((micromachined or micromachine or micromaching or (micro near machine\$3)) with (via or hole))	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:54
L15	95	L14 and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:55
L16	0	L13 and L15	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:55